

ABSTRACT OF THE INVENTION

[0063] A method and system of coating a polymer solution on a substrate such as a semiconductor wafer. The method includes providing a substrate. Dispensing a polymer solution onto the surface of the substrate using a pump. The pump is connected in-line with a buffer tank and a polymer solution source such that the pump draws the polymer solution from the polymer solution source and the buffer tank in a continuous fluid path to dispense the polymer solution. The polymer solution source is connected to a pressure source capable of causing a transfer of the polymer solution from the polymer solution source into the buffer tank. The buffer tank to maintain a relatively constant level of polymer solution.